

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A substrate for a device package comprising:
 - a lower portion of a package;
 - an intermediate metalization layer on a top surface of said lower portion;
 - an upper portion of said package on said top surface of said lower portion, a corner portion of said lower portion and a corresponding portion of said intermediate metalization layer extending beyond said upper portion such that said corresponding portion of said intermediate metalization layer is remaining visible beyond the extent of said upper portion ~~for indicating an orientation of said substrate~~ when viewed from a direction normal to said top surface.
2. (Original) The substrate of Claim 1, said lower and upper portions comprising a ceramic.
3. (Original) The substrate of Claim 1, said lower portion comprising a layered ceramic portion containing electrical interconnections.
4. (Original) The substrate of Claim 1, said visible corner portion comprising a plating on said visible corner portion.
5. (Original) The substrate of Claim 1, comprising an electrical device electrically connected to portions of said metalization layer.
6. (Original) The substrate of Claim 1, comprising an electrical device electrically connected to portions of said metalization layer, said visible corner portion electrically isolated from said portions of said metalization layer electrically connected to said device.
7. (Original) The substrate of Claim 1, comprising an electrical device and a lid enclosing said device between said lid and said substrate.
8. (Original) The substrate of Claim 1, said upper portion having a void over said visible corner region of said metalization layer, said void allowing visibility to said metalization layer.
9. (Original) The substrate of Claim 8, said void used to mechanically position said substrate.
- 10-19. (Canceled)